

OS5MF3TEC1E

Anode

1.0

-2.1±0.2

Cathode

VER.3

Features

•Outline Dimension

12.0-0.3

- High-power LED
- Long lifetime operation
- Typical viewing angle : 120deg
- **RoHS** compliant •
- Possible to attach to heat sink directly without using print circuit board.

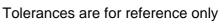
Applications

- Indoor & outdoor lighting
- Stage lighting
- Reading lamps
- Display cases, furniture illumination, marker
- Architectural illumination
- Spotlights

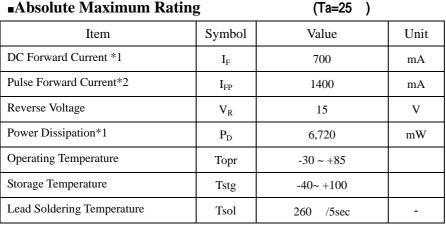
Absolute Maximum Rating

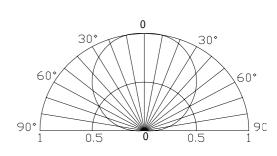
15.0^{+0.5} Unit:mm Tolerance:±0.30mm

-9.3



Directivity





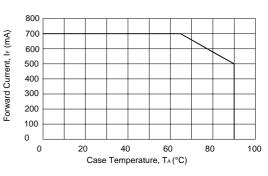
*1, Power dissipation and forward current are the value when the module temperature is

set lower than the rating by using an adequate heat sink.

*2, Pulse width Max.10ms Duty ratio max 1/10

Electrical -Optical Characteristics					(Ta=25)	
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
DC Forward Voltage	$V_{\rm F}$	I _F =600mA	9.0	9.6	10.8	V
DC Reverse Current	I _R	V _R =15V	-	-	100	μA
Luminous Flux	v	I _F =600mA	580	600	-	lm
Color Temperature	CCT	I _F =600mA	-	3000	-	K
Chromaticity	х	I _F =600mA	-	0.44	-	
Coordinates*	у	I _F =600mA	-	0.41	-	
50% Power Angle	2 0 1/2	I _F =600mA	-	120	-	deg

<Fig.a> Forward Current Derating Curve



Note: Don't drive at rated current more than 5s without heat sink for High Power series.

* Tolerance of chromaticity coordinates is +10%,

* Tolerance of Luminous Flux is +20%

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Tops 6W Warm White Ceramic LED

OS5MF3TEC1E

VER.3

Heat design

The following pictures show some measurements of mounted 5W Led on the heat sink for each board A and B (See Fig 1) with using thermograph to make an observation about heat distribution. Each boards is tested at various current conditions. As a result, LED needs larger heat sink as much as possible to reduce its own case temperature.

rig. 1 Configuration pattern examples for board assembly							
Board	LED power	Material	Surface area (mm²) Min.				
А	5W	Al	10,300				
В	10W	Al	20,600				
С	25W	Al	51,500				
D	50W	Al	103,000				
Е	100W	Al	206,000				
F	200W	Al	412,000				
G	300W	Al	618,000				

Fig. 1 Configuration pattern examples for board assembly

Above tested LED device is attached with adhesive sheet to the heatsink.

For reference's sake, Tj absolute maximum rating is defined at 115

<Fig.2> Board A (surface area=10,300mm²) IF=200mA IF=200mA 90°C 90°C 80°C 80°C 60°C 60°C 40°C 40°C 25°C 25°C IF=400mA IF=400mA 90°C 90°C 80°C 80°C 60°C 60°C 40°C 40°C 25°C 25°C IF=600mA IF=600mA 90°C 90°C 80°C 80°C 60°C 60°C 40°C 40°C 25°C 25°C

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<Fig.3> Board B (surface area=20,600 m²)

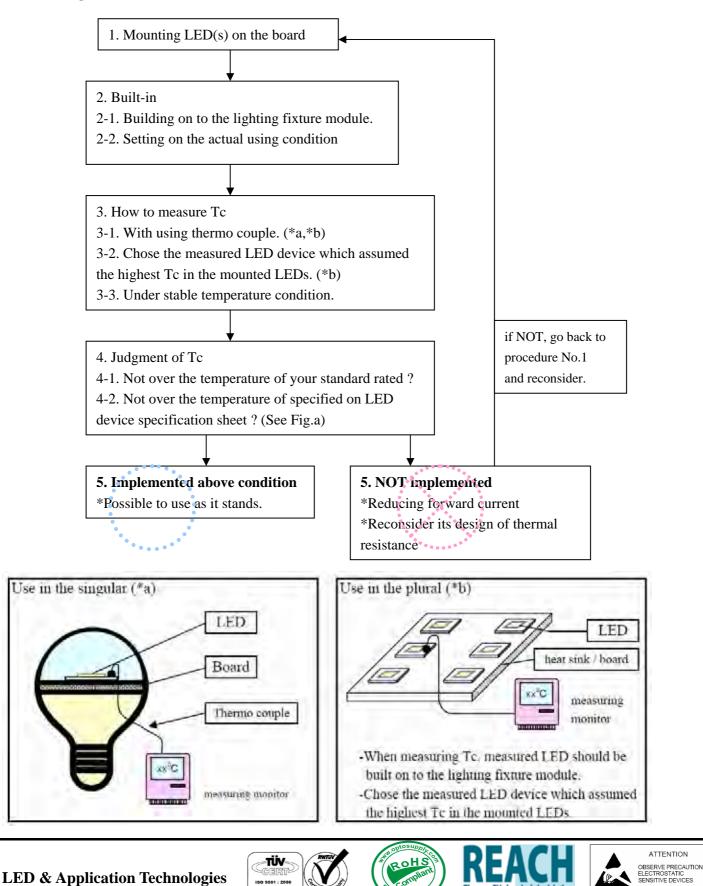
as a prerequisite on design process of 5W LED.



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Heat design→Design flow chart





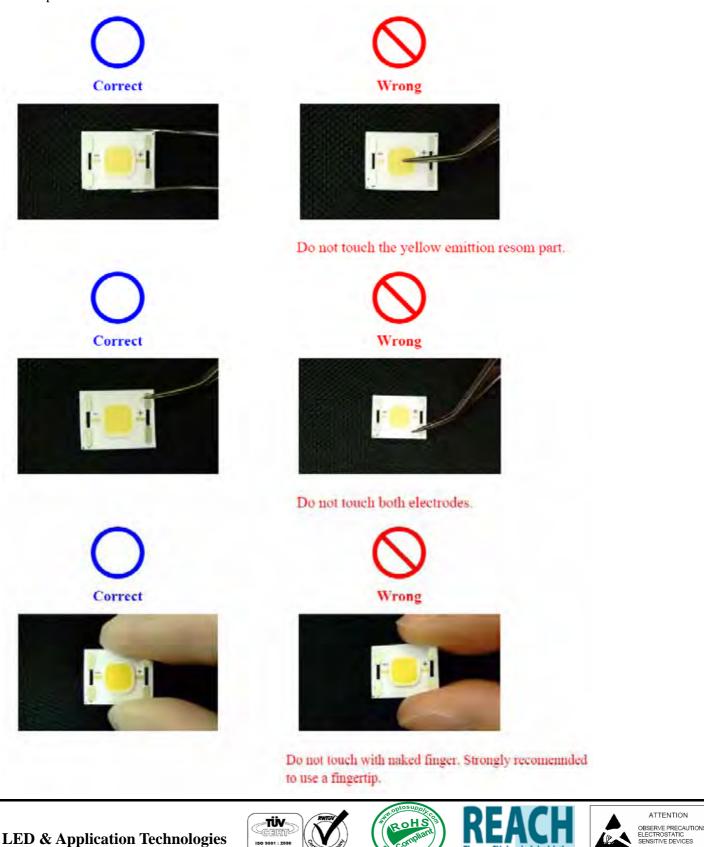
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Handling→Manually handling

Use tweezers to catch hold of LEDs at the base substrate part. Do not touch the lens with the tweezers and fingers. Do not press on the lens.



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